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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	4224
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	115
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TA)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax250-pqg208m

Two C-cells, a single R-cell, two Transmit (TX), and two Receive (RX) routing buffers form a Cluster, while two Clusters comprise a SuperCluster (Figure 1-4). Each SuperCluster also contains an independent Buffer (B) module, which supports buffer insertion on high-fanout nets by the place-and-route tool, minimizing system delays while improving logic utilization.

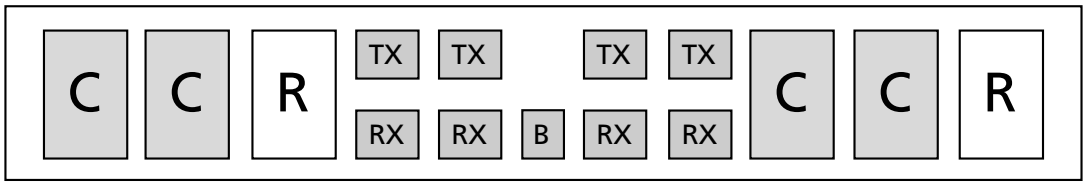

Figure 1-4 • **AX SuperCluster**

The logic modules within the SuperCluster are arranged so that two combinatorial modules are side-by-side, giving a C–C–R – C–C–R pattern to the SuperCluster. This C–C–R pattern enables efficient implementation (minimum delay) of two-bit carry logic for improved arithmetic performance (Figure 1-5 on page 1-3).

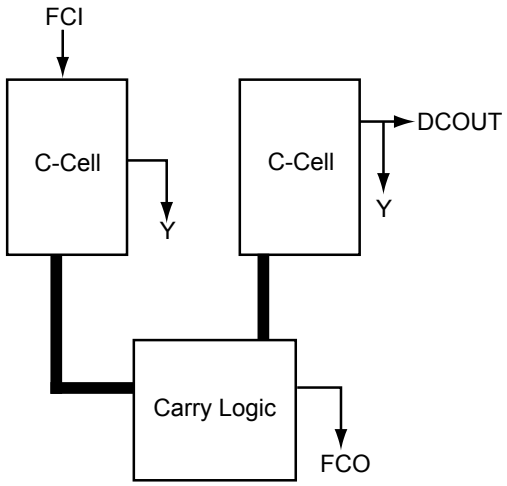

Figure 1-5 • **AX 2-Bit Carry Logic**

The AX architecture is fully fracturable, meaning that if one or more of the logic modules in a SuperCluster are used by a particular signal path, the other logic modules are still available for use by other paths.

At the chip level, SuperClusters are organized into core tiles, which are arrayed to build up the full chip. For example, the AX1000 is composed of a 3x3 array of nine core tiles. Surrounding the array of core tiles are blocks of I/O Clusters and the I/O bank ring (Table 1-1). Each core tile consists of an array of 336 SuperClusters and four SRAM blocks (176 SuperClusters and three SRAM blocks for the AX250).

Table 1-1 • **Number of Core Tiles per Device**

Device	Number of Core Tiles
AX125	1 regular tile
AX250	4 smaller tiles
AX500	4 regular tiles
AX1000	9 regular tiles
AX2000	16 regular tiles

2 – Detailed Specifications

Operating Conditions

Table 2-1 lists the absolute maximum ratings of Axcelerator devices. Stresses beyond the ratings may cause permanent damage to the device. Exposure to Absolute Maximum rated conditions for extended periods may affect device reliability. Devices should not be operated outside the recommendations in Table 2-2.

Table 2-1 • **Absolute Maximum Ratings**

Symbol	Parameter	Limits	Units
VCCA	DC Core Supply Voltage	–0.3 to 1.7	V
VCCI	DC I/O Supply Voltage	–0.3 to 3.75	V
VREF	DC I/O Reference Voltage	–0.3 to 3.75	V
VI	Input Voltage	–0.5 to 4.1	V
VO	Output Voltage	–0.5 to 3.75	V
TSTG	Storage Temperature	–60 to +150	°C
VCCDA*	Supply Voltage for Differential I/Os	–0.3 to 3.75	V

*Note: * Should be the maximum of all VCCI.*

Table 2-2 • **Recommended Operating Conditions**

Parameter Range	Commercial	Industrial	Military	Units
Ambient Temperature (T_A)[1]	0 to +70	–40 to +85	–55 to +125	°C
1.5 V Core Supply Voltage	1.425 to 1.575	1.425 to 1.575	1.425 to 1.575	V
1.5 V I/O Supply Voltage	1.425 to 1.575	1.425 to 1.575	1.425 to 1.575	V
1.8 V I/O Supply Voltage	1.71 to 1.89	1.71 to 1.89	1.71 to 1.89	V
2.5 V I/O Supply Voltage	2.375 to 2.625	2.375 to 2.625	2.375 to 2.625	V
3.3 V I/O Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V
VCCDA Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V
VPUMP Supply Voltage	3.0 to 3.6	3.0 to 3.6	3.0 to 3.6	V

Notes:

1. *Ambient temperature (T_A) is used for commercial and industrial grades; case temperature (T_C) is used for military grades.*
2. *T_J max = 125°C*

Power-Up/Down Sequence

All Axcelerator I/Os are tristated during power-up until normal device operating conditions are reached, when I/Os enter user mode. VCCDA should be powered up before (or coincidentally with) VCCA and VCCI to ensure the behavior of user I/Os at system start-up. Conversely, VCCDA should be powered down after (or coincidentally with) VCCA and VCCI. Note that VCCI and VCCA can be powered up in any sequence with respect to each other, provided the requirement with respect to VCCDA is satisfied.

Poutputs = PI/O * po * Fpo

C_{load} = the output load (technology dependent)
VCCI = the output voltage (technology dependent)
po = the number of outputs
F_{po} = the average output frequency

Pmemory = P11 * Nblock * FRCLK + P12 * Nblock * FWCLK

N_{block} = the number of RAM/FIFO blocks (1 block = 4k)
F_{RCLK} = the read-clock frequency of the memory
F_{WCLK} = the write-clock frequency of the memory

PPLL = P13 * FCLK

F_{RefCLK} = the clock frequency of the clock input of the PLL
F_{CLK} = the clock frequency of the first clock output of the PLL

Power Estimation Example

This example employs an AX1000 shift-register design with 1,080 R-cells, one C-cell, one reset input, and one LVTTL 12 mA output, with high slew.

This design uses one HCLK at 100 MHz.

ms = 1,080 (in a shift register - 100% of R-cells are toggling at each clock cycle)
Fs = 100 MHz
s = 1080
=> P_{HCLK} = (P1 + P2 * s + P3 * sqrt[s]) * Fs = 79 mW
and Fs = 100 MHz
=> $P_{R\text{-}cells}$ = P7 * ms * Fs = 173 mW
mc = 1 (1 C-cell in this shift-register)
and Fs = 100 MHz
=> $P_{C\text{-}cells}$ = P8 * mc * Fs = 0.14 mW
F_{pi} ~ 0 MHz
and pi= 1 (1 reset input => this is why F_{pi}=0)
=> P_{inputs} = P9 * pi * F_{pi} = 0 mW
F_{po} = 50 MHz
and po = 1
=> $P_{outputs}$ = $P_{I/O}$ * po * F_{po}= 27.10 mW
No RAM/FIFO in this shift-register
=> P_{memory} = 0 mW
No PLL in this shift-register
=> P_{PLL} = 0 mW
$P_{ac} = P_{HCLK} + P_{CLK} + P_{R\text{-}cells} + P_{C\text{-}cells} + P_{inputs} + P_{outputs} + P_{memory} + P_{PLL}$ = 276 mW
P_{dc} = 7.5mA * 1.5V = 11.25 mW
$P_{total} = P_{dc} + P_{ac}$ = 11.25 mW + 276mW = 290.30 mW

***Table 2-22* • 3.3 V LVTTL I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
LVTTL Output Drive Strength = 2 (12 mA) / High Slew Rate								
t_{DP}	Input Buffer		1.68		1.92		2.26	ns
t_{PY}	Output Buffer		3.30		3.76		4.42	ns
t_{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.74		4.26		5.00	ns
t_{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		3.06		3.49		4.10	ns
t_{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.89		1.91		1.91	ns
t_{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.29		2.30		2.31	ns
t_{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t_{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses an LVTTL input buffer and a push-pull output buffer. The input and output buffers are 5 V tolerant with the aid of external components. Axcelerator 3.3 V PCI and 3.3 V PCI-X buffers are compliant with the PCI Local Bus Specification Rev. 2.1.

The PCI Compliance Specification requires the clamp diodes to be able to withstand for 11 ns, –3.5 V in undershoot, and 7.1 V in overshoot.

***Table 2-33* • DC Input and Output Levels**

	VIL		VIH		VOL	VOH	IOL	IOH
	Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
PCI	–0.3	0.3 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			
PCI-X	–0.5	0.35 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			

AC Loadings

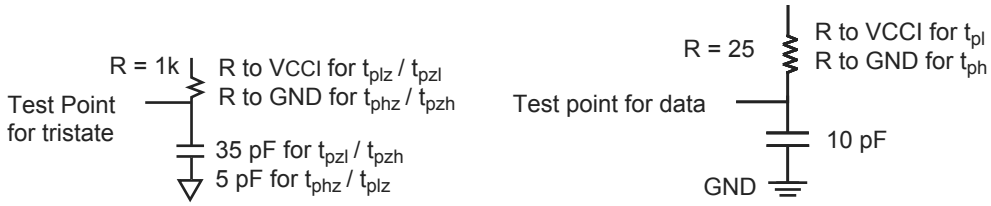

***Figure 2-18 •* AC Test Loads**

***Table 2-34* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
(Per PCI Spec and PCI-X Spec)			N/A	10

*Note: * Measuring Point = VTRIP*

SSTL2

Stub Series Terminated Logic for 2.5 V is a general-purpose 2.5 V memory bus standard (JESD8-9). The Axcelerator devices support both classes of this standard. This requires a differential amplifier input buffer and a push-pull output buffer.

Class I

***Table 2-44* • DC Input and Output Levels**

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	**Max., V**	**Min., V**	**Max., V**	**Max., V**	**Min., V**	**mA**	**mA**
–0.3	VREF – 0.2	VREF + 0.2	3.6	VREF – 0.57	VREF + 0.57	7.6	–7.6

AC Loadings

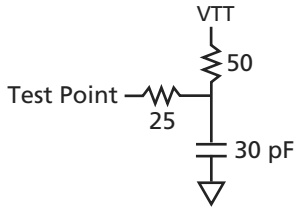

***Figure 2-21* • AC Test Loads**

***Table 2-45* • AC Waveforms, Measuring Points, and Capacitive Loads**

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C_{load} (pF)
VREF – 0.75	VREF + 0.75	VREF	1.25	30

*Note: * Measuring Point = VTRIP*

Timing Characteristics

***Table 2-46* • 2.5 V SSTL2 Class I I/O Module**
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	**Description**	**Min.**	**Max.**	**Min.**	**Max.**	**Min.**	**Max.**	**Units**
2.5 V SSTL2 Class I I/O Module Timing								
t_{DP}	Input Buffer		1.83		2.08		2.45	ns
t_{PY}	Output Buffer		2.39		2.72		3.20	ns
t_{ICLKQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t_{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t_{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t_{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t_{HD}	Data Input Hold		0.00		0.00		0.00	ns
t_{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t_{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t_{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t_{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t_{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t_{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t_{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t_{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

The HM and CM modules can select between:

- The HCLK or CLK source respectively
- A local signal routed on generic routing resources

This allows each core tile to have eight clocks independent of the other core tiles in the device.

Both HCLK and CLK are segmentable, meaning that individual branches of the global resource can be used independently.

Like the HM and CM modules, the HD and RD modules can select between:

- The HCLK or CLK source from the HM or CM module respectively
- A local signal routed on generic routing resources

The AX architecture is capable of supporting a large number of local clocks—24 segments per HCLK driving north-south and 28 segments per CLK driving east-west per core tile.

Microsemi's Designer software's place-and-route takes advantage of the segmented clock structure found in Axcelerator devices by turning off any unused clock segments. This results in not only better performance but also lower power consumption.

Global Resource Access Macros

Global resources can be driven by one of three sources: external pad(s), an internal net, or the output of a PLL. These connections can be made by using one of three types of macros: CLKBUF, CLKINT, and PLLCLK.

CLKBUF and HCLKBUF

CLKBUF (HCLKBUF) is used to drive a CLK (HCLK) from external pads. These macros can be used either generically or with the specific I/O standard desired (e.g. CLKBUF_LVCMOS25, HCLKBUF_LVDS, etc.) (Figure 2-42).

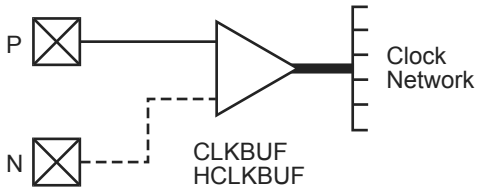

Figure 2-42 • **CLKBUF and HCLKBUF**

Package pins CLKEP and CLKEN are associated with CLKE; package pins HCLKAP and HCLKAN are associated with HCLKA, etc.

Note that when CLKBUF (HCLKBUF) is used with a single-ended I/O standard, it must be tied to the P-pad of the CLK (HCLK) package pin. In this case, the CLK (HCLK) N-pad can be used for user signals.

CLKINT and HCLKINT

CLKINT (HCLKINT) is used to access the CLK (HCLK) resource internally from the user signals (Figure 2-43).

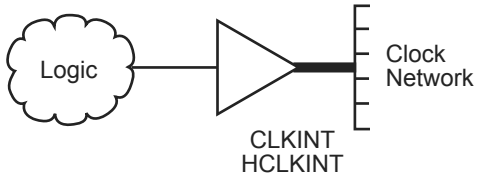

Figure 2-43 • **CLKINT and HCLKINT**

PLLRCLK and PLLHCLK

PLLRCLK (PLLHCLK) is used to drive global resource CLK (HCLK) from a PLL (Figure 2-44).

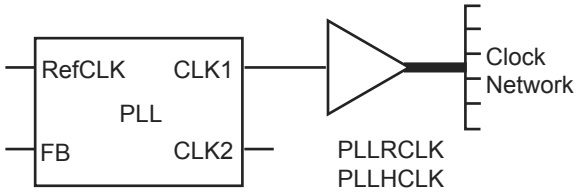

Figure 2-44 • **PLLRCLK and PLLHCLK**

Using Global Resources with PLLs

Each global resource has an associated PLL at its root. For example, PLLA can drive HCLKA, PLLE can drive CLKE, etc. (Figure 2-45).

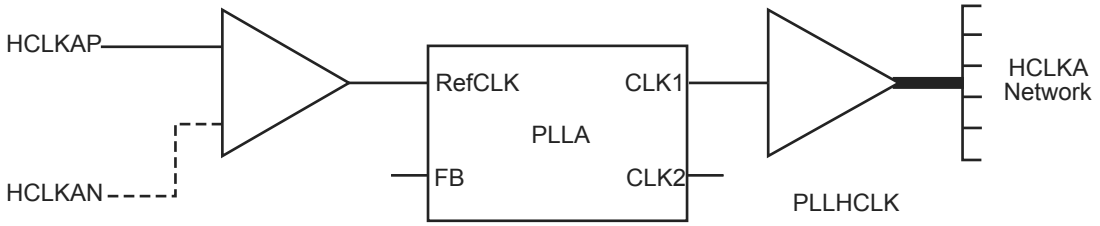

Figure 2-45 • **Example of HCLKA Driven from a PLL with External Clock Source**

In addition, each clock pin of the package can be used to drive either its associated global resource or PLL. For example, package pins CLKEP and CLKEN can drive either the RefCLK input of PLLE or CLKE.

There are two macros required when interfacing the embedded PLLs with the global resources: PLLINT and PLLOUT.

PLLINT

This macro is used to drive the RefCLK input of the PLL internally from user signals.

PLLOUT

This macro is used to connect either the CLK1 or CLK2 output of a PLL to the regular routing network (Figure 2-46).

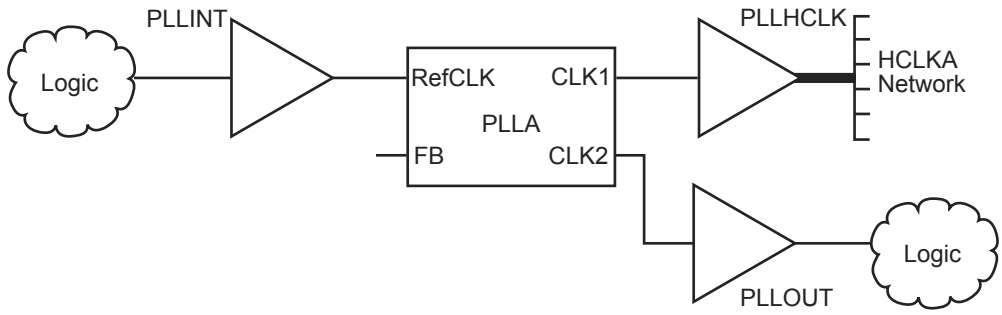

Figure 2-46 • **Example of PLLINT and PLLOUT Usage**

Special PLL Macros

Table 2-84 shows the macros used to connect the RefCLK input and CLK1 and CLK2 outputs using the different routing resources.

***Table 2-84* • PLL Special Macros**

Macro Name	Usage
PLLINT	Connects RefCLK to a regular routed net or a pad.
PLLRCLK	Connects CLK1 or CLK2 to the CLK network.
PLLHCLK	Connects CLK1 or CLK2 to the HCLK network.
PLLOUT	Connects CLK1 or CLK2 to a regular routed net.

***Table 2-85* • Electrical Specifications**

Parameter	Value	Notes
Frequency Ranges		
Reference Frequency (min.)	14 MHz	Lowest input frequency
Reference Frequency (max.)	200 MHz	Highest input frequency
OSC Frequency (min.)	20 MHz	Lowest output frequency
OSC Frequency (max.)	1 GHz	Highest output frequency
Jitter		
Long-Term Jitter (max.)	1%	Percentage of period, low reference clock frequencies
Long-Term Jitter (max.)	100ps	High reference clock frequencies
Short-Term Jitter (max.)	50ps+1%	Percentage of output frequency
Acquisition Time (lock) from Cold Start		
Acquisition Time (max.)*	400 cycles	Period of low reference clock frequencies
Acquisition Time (max.)*	1.5 µs	High reference clock frequencies
Power Consumption		
Analog Supply Current (low freq.)	200 µA	Current at minimum oscillator frequency
Analog Supply Current (high freq.)	200 µA	Frequency-dependent current
Digital Supply Current (low freq.)	0.5 µA/MHz	Current at maximum oscillator frequency, unloaded
Digital Supply Current (high freq.)	1 µA/MHz	Frequency-dependent current
Duty Cycle		
Minimum Output Duty Cycle	45%	
Maximum Output Duty Cycle	55%	

*Note: *The lock bit remains Low until RefCLK reaches the minimum input frequency.*

Glitch Elimination

An analog filter is added to each FIFO controller to guarantee glitch-free FIFO-flag logic.

Overflow and Underflow Control

The counter MSB keeps track of the difference between the read address (RA) and the write address (WA). The EMPTY flag is set when the read and write addresses are equal. To prevent underflow, the write address is double-sampled by the read clock prior to comparison with the read address (part A in Figure 2-64). To prevent overflow, the read address is double-sampled by the write clock prior to comparison to the write address (part B in Figure 2-64).

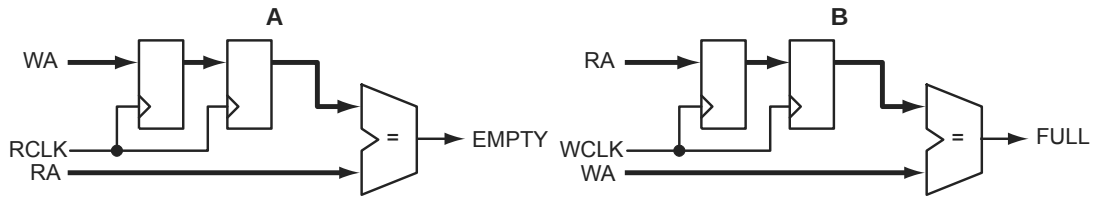

Figure 2-64 • **Overflow and Underflow Control**

FIFO Configurations

Unlike the RAM, the FIFO's write width and read width cannot be specified independently. For the FIFO, the write and read widths must be the same. The WIDTH pins are used to specify one of six allowable word widths, as shown in Table 2-96.

Table 2-96 • **FIFO Width Configurations**

WIDTH(2:0)	W x D
000	1 x 4k
001	2 x 2k
010	4 x 1k
011	9 x 512
100	18 x 256
101	36 x 128
11x	reserved

The DEPTH pins allow RAM cells to be cascaded to create larger FIFOs. The four pins allow depths of 2, 4, 8, and 16 to be specified. Table 2-86 on page 2-87 describes the FIFO depth options for various data width and memory blocks.

Interface

Figure 2-65 on page 2-99 shows a logic block diagram of the Axcelerator FIFO module.

Cascading FIFO Blocks

FIFO blocks can be cascaded to create deeper FIFO functions. When building larger FIFO blocks, if the word width can be fractured in a multi-bit FIFO, the fractured word configuration is recommended over a cascaded configuration. For example, 256x36 can be configured as two blocks of 256x18. This should be taken into account when building the FIFO blocks manually. However, when using SmartGen, the user only needs to specify the depth and width of the necessary FIFO blocks. SmartGen automatically configures these blocks to optimize performance.

Clock

As with RAM configuration, the RCLK and WCLK pins have independent polarity selection.

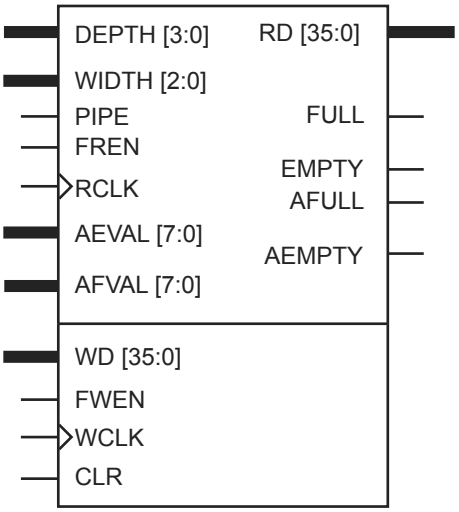

Figure 2-65 • **FIFO Block Diagram**

Table 2-97 • **FIFO Signal Description**

Signal	Direction	Description
WCLK	Input	Write clock (active either edge).
FWEN	Input	FIFO write enable. When this signal is asserted, the WD bus data is latched into the FIFO, and the internal write counters are incremented.
WD[N-1:0]	Input	Write data bus. The value N is dependent on the RAM configuration and can be 1, 2, 4, 9, 18, or 36.
FULL	Output	Active high signal indicating that the FIFO is FULL. When this signal is set, additional write requests are ignored.
AFULL	Output	Active high signal indicating that the FIFO is AFULL.
AFVAL	Input	8-bit input defining the AFULL value of the FIFO.
RCLK	Input	Read clock (active either edge).
FREN	Input	FIFO read enable.
RD[N-1:0]	Output	Read data bus. The value N is dependent on the RAM configuration and can be 1, 2, 4, 9, 18, or 36.
EMPTY	Output	Empty flag indicating that the FIFO is EMPTY. When this signal is asserted, attempts to read the FIFO will be ignored.
AEMPTY	Output	Active high signal indicating that the FIFO is AEMPTY.
AEVAL	Input	8-bit input defining the almost-empty value of the FIFO.
PIPE	Input	Sets the pipe option on or off.
CLR	Input	Active high clear input.
DEPTH	Input	Determines the depth of the FIFO and the number of FIFOs to be cascaded.
WIDTH	Input	Determines the width of the dataword/FIFO, and the number of the FIFOs to be cascaded.

mode if desired. Please note, if the I/O bank is not disabled, differential I/Os belonging to the I/O bank will still consume normal power, even when operating in the low power mode.

The Axcelerator device will resume normal operation 10µs after the LP pin is pulled Low.

To further reduce power consumption, the internal charge pump can be bypassed and an external power supply voltage can be used instead. This saves the internal charge-pump operating current, resulting in no DC current draw. The Axcelerator family devices have a dedicated "V_{PUMP}" pin that can be used to access an external charge pump device. In normal chip operation, when using the internal charge pump, V_{PUMP} should be tied to GND. When the voltage level on V_{PUMP} is set to 3.3V, the internal charge pump is turned off, and the V_{PUMP} voltage will be used as the charge pump voltage. Adequate voltage regulation (i.e. high drive, low output impedance, and good decoupling) should be used at V_{PUMP}.

In addition, any PLL in use can be powered down to further reduce power consumption. This can be done with the PowerDown pin driven Low. Driving this pin High restarts the PLL with the output clock(s) being stable once lock is restored.

JTAG

Axcelerator offers a JTAG interface that is compliant with the IEEE 1149.1 standard. The user can employ the JTAG interface for probing a design and performing any JTAG Public Instructions as defined in the Table 2-103.

***Table 2-103* • JTAG Instruction Code**

Instruction (IR4:IR0)	Binary Code
Extest	00000
Preload / Sample	00001
Intest	00010
USERCODE	00011
IDCODE	00100
HIGHZ	01110
CLAMP	01111
Diagnostic	10000
Reserved	All others
Bypass	11111

Interface

The interface consists of four inputs: Test Mode Select (TMS), Test Data In (TDI), Test Clock (TCK), TAP Controller Reset (TRST), and an output, Test Data Out (TDO). TMS, TDI, and TRST have on-chip pull-up resistors.

TRST

TRST (Test-Logic Reset) is an active-low, asynchronous reset signal to the TAP controller. The TRST input can be used to reset the Test Access Port (TAP) Controller to the TRST state. The TAP Controller can be held at this state permanently by grounding the TRST pin. To hold the JTAG TAP controller in the TRST state, it is recommended to connect TRST to ground via a 1 kΩ resistor.

There is an optional internal pull-up resistor available for the TRST input that can be set by the user at programming. Care should be exercised when using this option in combination with an external tie-off to ground.

An on-chip power-on-reset (POWRST) circuit is included. POWRST has the same function as "TRST," but it only occurs at power-up or during recovery from a VCCA and/or VCCDA voltage drop.

BG729	
AX1000 Function	Pin Number
IO109NB3F10	V24
IO109PB3F10	V25
IO110NB3F10	T20
IO110PB3F10	T21
IO111NB3F10	W26
IO111PB3F10	W27
IO112NB3F10	U22
IO112PB3F10	U23
IO113NB3F10	Y26
IO113PB3F10	Y27
IO114NB3F10	U20
IO114PB3F10	U21
IO115NB3F10	W24
IO115PB3F10	W25
IO116NB3F10	V22
IO116PB3F10	V23
IO117NB3F10	Y24
IO117PB3F10	Y25
IO118NB3F11	V20
IO118PB3F11	V21
IO119NB3F11	AA26
IO119PB3F11	AA27
IO120NB3F11	W22
IO120PB3F11	W23
IO121NB3F11	AA24
IO121PB3F11	AA25
IO122NB3F11	W20
IO122PB3F11	W21
IO123NB3F11	AB26
IO123PB3F11	AB27
IO124NB3F11	Y22
IO124PB3F11	Y23
IO125NB3F11	AB24
IO125PB3F11	AB25
IO126NB3F11	AA22
IO126PB3F11	AA23
IO127NB3F11	AC26

BG729	
AX1000 Function	Pin Number
IO127PB3F11	AC27
IO128NB3F11	Y20
IO128PB3F11	W19
Bank 4	
IO129NB4F12	AA20
IO129PB4F12	Y21
IO130NB4F12	AB22
IO130PB4F12	AB23
IO131NB4F12	AC22
IO131PB4F12	AC23
IO132NB4F12	AD23
IO132PB4F12	AD24
IO133NB4F12	AF23
IO133PB4F12	AE23
IO134NB4F12	AC21
IO134PB4F12	AB21
IO135NB4F12	AC20
IO135PB4F12	AB20
IO136NB4F12	AD21
IO136PB4F12	AD22
IO137NB4F12	Y19
IO137PB4F12	AA19
IO138NB4F12	AE21
IO138PB4F12	AE22
IO139NB4F13	AF21
IO139PB4F13	AF22
IO140NB4F13	AG22
IO140PB4F13	AG23
IO141NB4F13	Y18
IO141PB4F13	AA18
IO142NB4F13	AE20
IO142PB4F13	AD20
IO143NB4F13	AG20
IO143PB4F13	AG21
IO144NB4F13	AC19
IO144PB4F13	AB19
IO145NB4F13	AD18

BG729	
AX1000 Function	Pin Number
IO145PB4F13	AD19
IO146NB4F13	AC18
IO146PB4F13	AB18
IO147NB4F13	Y17
IO147PB4F13	AA17
IO148NB4F13	AF19
IO148PB4F13	AF20
IO149NB4F13	AC17
IO149PB4F13	AB17
IO150NB4F13	AE18
IO150PB4F13	AE19
IO151NB4F13	AA16
IO151PB4F13	Y16
IO152NB4F14	AG18
IO152PB4F14	AG19
IO153NB4F14	AC16
IO153PB4F14	AB16
IO154NB4F14	AF17
IO154PB4F14	AF18
IO155NB4F14	AB15
IO155PB4F14	AC15
IO156NB4F14	AE16
IO156PB4F14	AE17
IO157NB4F14	Y15
IO157PB4F14	AA15
IO158NB4F14	AG16
IO158PB4F14	AG17
IO159NB4F14/CLKEN	AF15
IO159PB4F14/CLKEP	AF16
IO160NB4F14/CLKFN	AD14
IO160PB4F14/CLKFP	AD15
Bank 5	
IO161NB5F15/CLKGN	AE14
IO161PB5F15/CLKGP	AE15
IO162NB5F15/CLKHN	AC13
IO162PB5F15/CLKHP	AD13
IO163NB5F15	Y14

FG676	
AX500 Function	Pin Number
GND	R10
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A11
NC	A21

FG676	
AX500 Function	Pin Number
NC	A22
NC	A24
NC	A25
NC	AA11
NC	AA19
NC	AA20
NC	AA4
NC	AA5
NC	AA6
NC	AA7
NC	AA8
NC	AA9
NC	AB1
NC	AB11
NC	AB17
NC	AB18
NC	AB19
NC	AB20
NC	AB8
NC	AB9
NC	AC1
NC	AC13
NC	AC14
NC	AC25
NC	AD1
NC	AD11
NC	AD16
NC	AD25
NC	AE1
NC	AF2
NC	AF25
NC	B11
NC	B24
NC	B4
NC	C16

FG676	
AX500 Function	Pin Number
NC	C4
NC	D1
NC	D13
NC	D14
NC	D17
NC	D18
NC	D2
NC	D26
NC	D3
NC	D9
NC	E1
NC	E18
NC	E23
NC	E24
NC	E26
NC	E3
NC	E4
NC	E9
NC	F1
NC	F18
NC	F20
NC	F21
NC	F22
NC	F23
NC	F24
NC	F4
NC	F6
NC	F7
NC	G21
NC	G22
NC	H21
NC	H22
NC	H23
NC	H5
NC	H6

FG896	
AX1000 Function	Pin Number
NC	K1
NC	K2
NC	L30
NC	M30
NC	N29
NC	T1
NC	U1
NC	W30
NC	Y1
NC	Y2
NC	Y30
PRA	G15
PRB	D16
PRC	AB16
PRD	AF16
TCK	G7
TDI	D5
TDO	J8
TMS	F6
TRST	C4
VCCA	AD6
VCCA	AH26
VCCA	E28
VCCA	E3
VCCA	L12
VCCA	L13
VCCA	L14
VCCA	L15
VCCA	L16
VCCA	L17
VCCA	L18
VCCA	L19
VCCA	M11
VCCA	M20
VCCA	N11

FG896	
AX1000 Function	Pin Number
VCCA	N20
VCCA	P11
VCCA	P20
VCCA	R11
VCCA	R20
VCCA	T11
VCCA	T20
VCCA	U11
VCCA	U20
VCCA	V11
VCCA	V20
VCCA	W11
VCCA	W20
VCCA	Y12
VCCA	Y13
VCCA	Y14
VCCA	Y15
VCCA	Y16
VCCA	Y17
VCCA	Y18
VCCA	Y19
VCCPLA	G14
VCCPLB	H15
VCCPLC	G17
VCCPLD	J16
VCCPLE	AH17
VCCPLF	AC16
VCCPLG	AH14
VCCPLH	AD15
VCCDA	AD24
VCCDA	AD7
VCCDA	AF12
VCCDA	AF13
VCCDA	AF15
VCCDA	AF18

FG896	
AX1000 Function	Pin Number
VCCDA	AF19
VCCDA	C13
VCCDA	C5
VCCDA	D13
VCCDA	D19
VCCDA	D3
VCCDA	E18
VCCDA	F26
VCCDA	G16
VCCDA	T25
VCCDA	T4
VCCIB0	A3
VCCIB0	B3
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K11
VCCIB0	K12
VCCIB0	K13
VCCIB0	K14
VCCIB0	K15
VCCIB1	A28
VCCIB1	B28
VCCIB1	J19
VCCIB1	J20
VCCIB1	J21
VCCIB1	K16
VCCIB1	K17
VCCIB1	K18
VCCIB1	K19
VCCIB1	K20
VCCIB2	C29
VCCIB2	C30
VCCIB2	K22
VCCIB2	L21

FG896	
AX2000 Function	**Pin Number**
IO303PB7F28	R1
IO304NB7F28	R7
IO304PB7F28	R6
IO306NB7F28	N2
IO306PB7F28	P2
IO307NB7F28	N3
IO307PB7F28	P3
IO308NB7F28	P9
IO308PB7F28	P8
IO309NB7F28	P4
IO309PB7F28	P5
IO310NB7F29	P7
IO310PB7F29	P6
IO311NB7F29	L1
IO311PB7F29	M1
IO312NB7F29	M5
IO312PB7F29	N5
IO313NB7F29	M4
IO313PB7F29	N4
IO315NB7F29	L2
IO315PB7F29	M2
IO316NB7F29	N7
IO316PB7F29	N6
IO317NB7F29	L3
IO317PB7F29	M3
IO318NB7F29	N8
IO318PB7F29	N9
IO320NB7F29	L6
IO320PB7F29	M6
IO321NB7F30	K4
IO321PB7F30	L4
IO322NB7F30	M8
IO322PB7F30	M7
IO323NB7F30	J1
IO323PB7F30	K1

FG896	
AX2000 Function	**Pin Number**
IO324NB7F30	K5
IO324PB7F30	L5
IO326NB7F30	G1*
IO326PB7F30	K2*
IO327NB7F30	J4
IO327PB7F30	J3
IO328NB7F30	L8
IO328PB7F30	L7
IO329NB7F30	G2
IO329PB7F30	H2
IO330NB7F30	G3
IO330PB7F30	H3
IO331NB7F30	K8
IO331PB7F30	K7
IO332NB7F31	J6
IO332PB7F31	K6
IO333NB7F31	D1
IO333PB7F31	D2
IO334NB7F31	G4
IO334PB7F31	H4
IO335NB7F31	F2
IO335PB7F31	F1
IO336NB7F31	H5
IO336PB7F31	J5
IO337NB7F31	E2
IO337PB7F31	E1
IO338NB7F31	H7
IO338PB7F31	J7
IO339NB7F31	F4
IO339PB7F31	F3
IO340NB7F31	F5
IO340PB7F31	G5
IO341NB7F31	G6
IO341PB7F31	H6
Dedicated I/O	

FG896	
AX2000 Function	**Pin Number**
GND	A13
GND	A18
GND	A2
GND	A23
GND	A29
GND	A8
GND	AA10
GND	AA21
GND	AA28
GND	AA3
GND	AB2
GND	AB22
GND	AB29
GND	AB9
GND	AC1
GND	AC30
GND	AE25
GND	AE6
GND	AF26
GND	AF5
GND	AG27
GND	AG4
GND	AH10
GND	AH15
GND	AH16
GND	AH21
GND	AH28
GND	AH3
GND	AJ1
GND	AJ2
GND	AJ22
GND	AJ29
GND	AJ30
GND	AJ9
GND	AK13

FG896	
AX2000 Function	Pin Number
GND	W19
GND	Y11
GND	Y20
GND/LP	E4
PRA	G15
PRB	D16
PRC	AB16
PRD	AF16
TCK	G7
TDI	D5
TDO	J8
TMS	F6
TRST	C4
VCCA	AD6
VCCA	AH26
VCCA	E28
VCCA	E3
VCCA	L12
VCCA	L13
VCCA	L14
VCCA	L15
VCCA	L16
VCCA	L17
VCCA	L18
VCCA	L19
VCCA	M11
VCCA	M20
VCCA	N11
VCCA	N20
VCCA	P11
VCCA	P20
VCCA	R11
VCCA	R20
VCCA	T11
VCCA	T20

FG896	
AX2000 Function	Pin Number
VCCA	U11
VCCA	U20
VCCA	V11
VCCA	V20
VCCA	W11
VCCA	W20
VCCA	Y12
VCCA	Y13
VCCA	Y14
VCCA	Y15
VCCA	Y16
VCCA	Y17
VCCA	Y18
VCCA	Y19
VCCDA	AD24
VCCDA	AD7
VCCDA	AE15
VCCDA	AE16
VCCDA	AF12
VCCDA	AF13
VCCDA	AF15
VCCDA	AF18
VCCDA	AF19
VCCDA	AH27
VCCDA	AH4
VCCDA	C13
VCCDA	C27
VCCDA	C5
VCCDA	D13
VCCDA	D19
VCCDA	D3
VCCDA	E18
VCCDA	F15
VCCDA	F16
VCCDA	F26

FG896	
AX2000 Function	Pin Number
VCCDA	G16
VCCDA	T25
VCCDA	T4
VCCIB0	A3
VCCIB0	B3
VCCIB0	J10
VCCIB0	J11
VCCIB0	J12
VCCIB0	K11
VCCIB0	K12
VCCIB0	K13
VCCIB0	K14
VCCIB0	K15
VCCIB1	A28
VCCIB1	B28
VCCIB1	J19
VCCIB1	J20
VCCIB1	J21
VCCIB1	K16
VCCIB1	K17
VCCIB1	K18
VCCIB1	K19
VCCIB1	K20
VCCIB2	C29
VCCIB2	C30
VCCIB2	K22
VCCIB2	L21
VCCIB2	L22
VCCIB2	M21
VCCIB2	M22
VCCIB2	N21
VCCIB2	P21
VCCIB2	R21
VCCIB3	AA22
VCCIB3	AH29

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

FG1152	
AX2000 Function	Pin Number
IO155PB3F14	AC29
IO156NB3F14	AE30
IO156PB3F14	AD30
IO157NB3F14	AC26
IO157PB3F14	AB26
IO158NB3F14	AH33
IO158PB3F14	AG33
IO159NB3F14	AD27
IO159PB3F14	AC27
IO160NB3F14	AG32
IO160PB3F14	AF32
IO161NB3F15	AG31
IO161PB3F15	AF31
IO162NB3F15	AF29
IO162PB3F15	AE29
IO163NB3F15	AE28
IO163PB3F15	AD28
IO164NB3F15	AG30
IO164PB3F15	AF30
IO165NB3F15	AE26
IO165PB3F15	AD26
IO166NB3F15	AJ30
IO166PB3F15	AH30
IO167NB3F15	AG28
IO167PB3F15	AF28
IO168NB3F15	AF27
IO168PB3F15	AE27
IO169NB3F15	AH29
IO169PB3F15	AG29
IO170NB3F15	AD25
IO170PB3F15	AC25
Bank 4	
IO171NB4F16	AP29
IO171PB4F16	AN29
IO172NB4F16	AH26

FG1152	
AX2000 Function	Pin Number
IO172PB4F16	AH27
IO173NB4F16	AJ27
IO173PB4F16	AJ28
IO174NB4F16	AL27
IO174PB4F16	AL28
IO175NB4F16	AM28
IO175PB4F16	AM29
IO176NB4F16	AG25
IO176PB4F16	AG26
IO177NB4F16	AK26
IO177PB4F16	AK27
IO178NB4F16	AF25
IO178PB4F16	AE25
IO179NB4F16	AP28
IO179PB4F16	AN28
IO180NB4F16	AJ25
IO180PB4F16	AJ26
IO181NB4F17	AM26
IO181PB4F17	AM27
IO182NB4F17	AF24
IO182PB4F17	AE24
IO183NB4F17	AH24
IO183PB4F17	AH25
IO184NB4F17	AG23
IO184PB4F17	AG24
IO185NB4F17	AL25
IO185PB4F17	AL26
IO186NB4F17	AP25
IO186PB4F17	AP26
IO187NB4F17	AK24
IO187PB4F17	AK25
IO188NB4F17	AF23
IO188PB4F17	AE23
IO189NB4F17	AN24
IO189PB4F17	AM24

FG1152	
AX2000 Function	Pin Number
IO190NB4F17	AH22
IO190PB4F17	AH23
IO191NB4F17	AJ23
IO191PB4F17	AJ24
IO192NB4F17	AG21
IO192PB4F17	AG22
IO193NB4F18	AP23
IO193PB4F18	AP24
IO194NB4F18	AN22
IO194PB4F18	AN23
IO195NB4F18	AM23
IO195PB4F18	AL23
IO196NB4F18	AF21
IO196PB4F18	AF22
IO197NB4F18	AL22
IO197PB4F18	AM22
IO198NB4F18	AE21
IO198PB4F18	AE22
IO199NB4F18	AJ21
IO199PB4F18	AJ22
IO200NB4F18	AK21
IO200PB4F18	AK22
IO201NB4F18	AM21
IO201PB4F18	AL21
IO202NB4F18	AE20
IO202PB4F18	AD20
IO203NB4F19	AN21
IO203PB4F19	AP21
IO204NB4F19	AP20
IO204PB4F19	AN20
IO205NB4F19	AN19
IO205PB4F19	AP19
IO206NB4F19	AG20
IO206PB4F19	AF20
IO207NB4F19	AL19

CQ208	
AX500 Function	Pin Number
Bank 0	
IO03NB0F0	198
IO03PB0F0	199
IO04NB0F0	197
IO19NB0F1/HCLKAN	191
IO19PB0F1/HCLKAP	192
IO20NB0F1/HCLKBN	185
IO20PB0F1/HCLKBP	186
Bank 1	
IO21NB1F2/HCLKCN	180
IO21PB1F2/HCLKCP	181
IO22NB1F2/HCLKDN	174
IO22PB1F2/HCLKDP	175
IO23NB1F2	170
IO23PB1F2	171
IO37NB1F3	165
IO37PB1F3	166
IO39NB1F3	161
IO39PB1F3	162
IO41NB1F3	159
IO41PB1F3	160
Bank 2	
IO43NB2F4	151
IO43PB2F4	153
IO44NB2F4	152
IO44PB2F4	154
IO45PB2F4	148
IO46NB2F4	146
IO46PB2F4	147
IO48NB2F4	144
IO48PB2F4	145
IO57NB2F5	139
IO57PB2F5	140
IO58PB2F5	141
IO59NB2F5	137
IO59PB2F5	138
IO61NB2F5	132

CQ208	
AX500 Function	Pin Number
IO61PB2F5	134
IO62NB2F5	131
IO62PB2F5	133
Bank 3	
IO63NB3F6	127
IO63PB3F6	129
IO64NB3F6	126
IO64PB3F6	128
IO66NB3F6	122
IO66PB3F6	123
IO68NB3F6	120
IO68PB3F6	121
IO77NB3F7	116
IO77PB3F7	117
IO79NB3F7	114
IO79PB3F7	115
IO81NB3F7	110
IO81PB3F7	111
IO82NB3F7	108
IO82PB3F7	109
IO83NB3F7	106
IO83PB3F7	107
Bank 4	
IO84PB4F8	103
IO85NB4F8	100
IO86NB4F8	101
IO86PB4F8	102
IO87NB4F8	96
IO87PB4F8	97
IO101NB4F9	91
IO101PB4F9	92
IO103NB4F9/CLKEN	87
IO103PB4F9/CLKEP	88
IO104NB4F9/CLKFN	81
IO104PB4F9/CLKFP	82
Bank 5	
IO105NB5F10/CLKGN	76

CQ208	
AX500 Function	Pin Number
IO105PB5F10/CLKGP	77
IO106NB5F10/CLKHN	70
IO106PB5F10/CLKHP	71
IO107NB5F10	66
IO107PB5F10	67
IO119NB5F11	62
IO121NB5F11	60
IO121PB5F11	61
IO123NB5F11	56
IO123PB5F11	57
IO125NB5F11	54
IO125PB5F11	55
Bank 6	
IO127NB6F12	47
IO127PB6F12	49
IO128NB6F12	48
IO128PB6F12	50
IO129NB6F12	42
IO129PB6F12	43
IO130PB6F12	44
IO132NB6F12	40
IO132PB6F12	41
IO141NB6F13	35
IO141PB6F13	36
IO142PB6F13	37
IO143NB6F13	33
IO143PB6F13	34
IO145NB6F13	28
IO145PB6F13	30
IO146NB6F13	27
IO146PB6F13	29
Bank 7	
IO147NB7F14	23
IO147PB7F14	25
IO148NB7F14	22
IO148PB7F14	24
IO150NB7F14	18

CG624	
AX2000 Function	**Pin Number**
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	T21
GND	T23
GND	T3
GND	T5
GND	V1
GND	V25
GND	V5
PRA	F13
PRB	A13
PRC	AB12
PRD	AE13
TCK	F5

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
TDI	C5
TDO	F6
TMS	D6
TRST	E6
VCCA	AB20
VCCA	F22
VCCA	F4
VCCA	J17
VCCA	J9
VCCA	K10
VCCA	K11
VCCA	K15
VCCA	K16
VCCA	L10
VCCA	L16
VCCA	R10
VCCA	R16
VCCA	T10
VCCA	T11
VCCA	T15
VCCA	T16
VCCA	U17
VCCA	U9
VCCA	Y4
VCCDA	A12
VCCDA	A14
VCCDA	AA13
VCCDA	AA15
VCCDA	AA20
VCCDA	AA7
VCCDA	AB13
VCCDA	AC11

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	**Pin Number**
VCCDA	AD11
VCCDA	AD4
VCCDA	AE12
VCCDA	AE17
VCCDA	B15
VCCDA	C15
VCCDA	C6
VCCDA	D13
VCCDA	E13
VCCDA	E19
VCCDA	F21
VCCDA	G10
VCCDA	G5
VCCDA	N21
VCCDA	N5
VCCDA	W21
VCCIB0	A3
VCCIB0	B3
VCCIB0	C4
VCCIB0	D5
VCCIB0	J10
VCCIB0	J11
VCCIB0	K12
VCCIB1	A23
VCCIB1	B23
VCCIB1	C22
VCCIB1	D21
VCCIB1	J15
VCCIB1	J16
VCCIB1	K14
VCCIB2	C24
VCCIB2	C25

*Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*